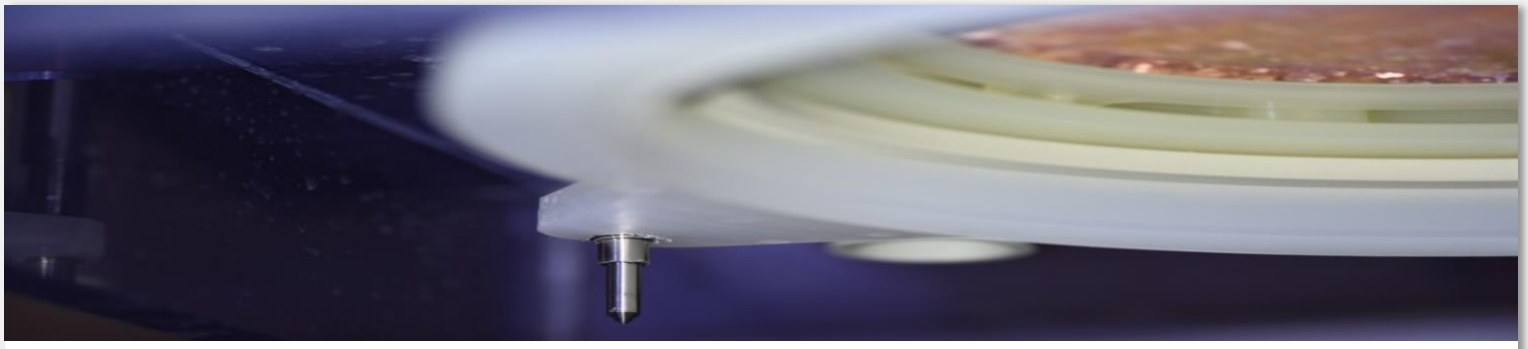
Wafer Face-Up Tool

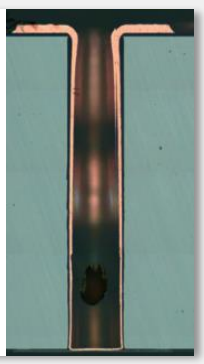
nb technologies
consulting engineers



In our **wafer face-up** electroplating system, the reaction chamber and wafer position is inverted, thus preventing air trapping during plating. The electrolyte flow is determined by the flow gap of the chamber and the pressure from the liquid column. The system can be used bench top system in standard fume hoods for research and development.

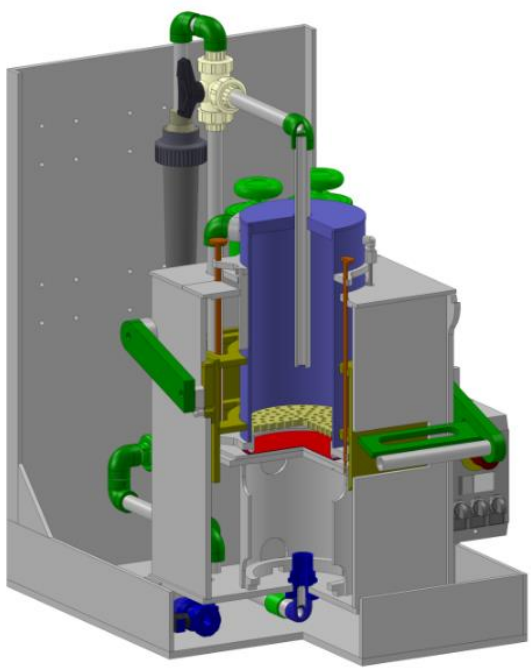
Application

- Through silicon via (Cu TSV)
- Plating at high aspect ratio
- Dual-damascene process



Features & Advantages

- Wafer face-up setup avoids air trapping
- Gravity assisted plating
- Substrate size: 100 mm, 150 mm, 200 mm
- Bath volume: 20 liters



October 2025

Headquarters Bremen

NB Technologies GmbH
Fahrenheitstr. 1
D-28359 Bremen
Germany

Phone: +49 (0) 421 2445810
Mail: info@nb-technologies.de

Site Cologne / Marsdorf

NB Technologies GmbH
Rheinische-Allee 3c
D-50858 Köln
Germany

Phone: +49 (0) 2234 20035 00

nb-technologies.de